1.1 Processor / Integrated Circuit Assembly Preparation

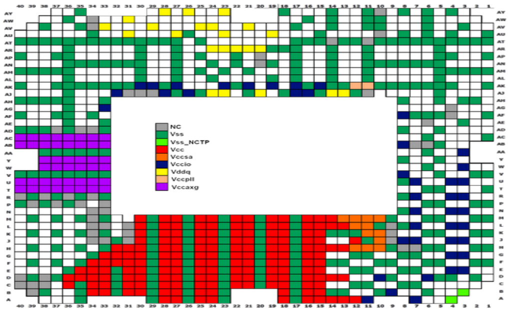

Figure 1

Standard-Category A
Test Result-Category B
Inspection-Category C

- Small deformations on processor pins, bends, or oxidation or contamination covering more than 5% of the pin surface.

- Gap between pin and socket exceeding pin diameter (D).

Note: JESD-51 (Thermal measurement standards for integrated circuits) contains additional information for implementing these requirements.

Inspection-Category B,C

- Incomplete seating in socket cavity.
- Failure to clean processor pins before mounting and socket connections (except LGA sockets)

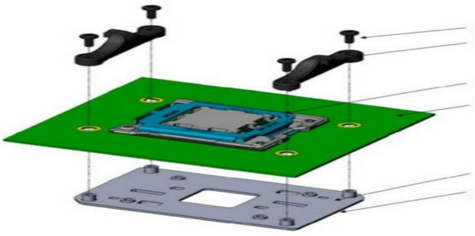

Figure 2

Test Requirements-Category A,B,C

- Scratches or damage on processor's usable surface that would affect thermal paste application.
- Excessive pressure affecting form, fit, and function.
- Loose mounting causing processor movement after heatsink installation.